



Product Change Notification

Change Notification #: 922890-00

Change Title: Intel® Ethernet Controllers I350-AM2 and I350-AM4

Change Detail: Shipping Tray Change

Date of Publication: August 14, 2026

Key Characteristics of the Change:

Transport Media

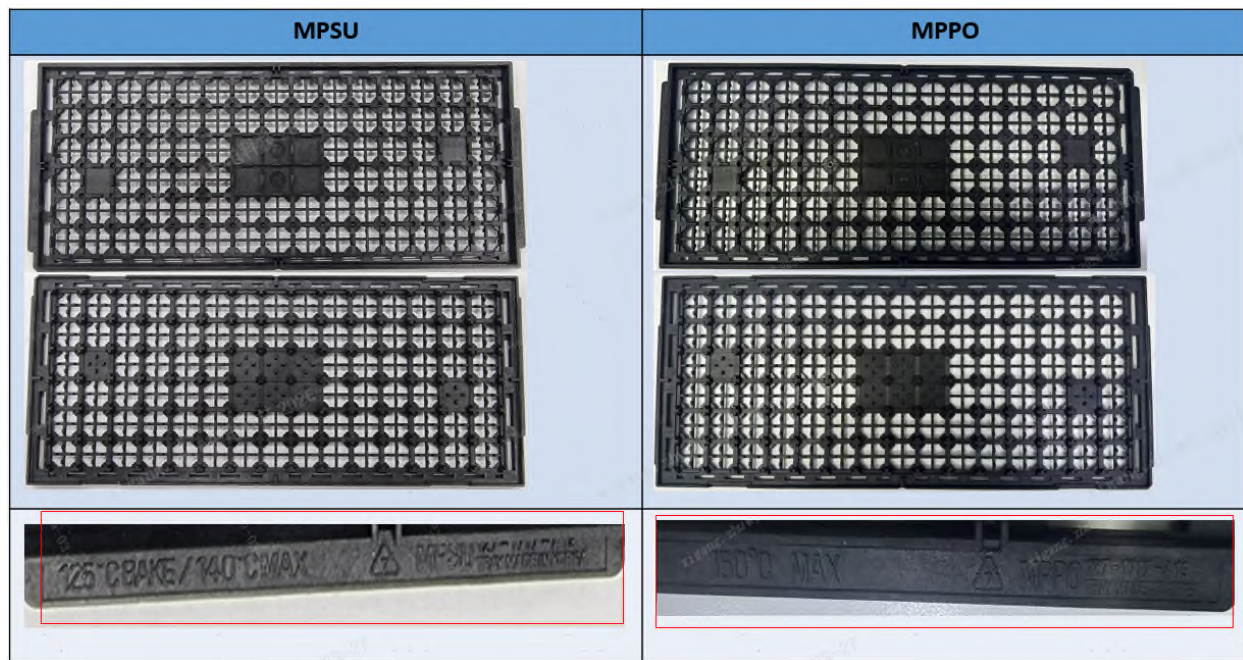
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	September 30, 2026
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Description of Change to the Customer:

Intel is changing the outbound Tray used to ship finished good products to customers. As of September 30, 2026, Intel will cut over to using a different tray to ship tray units to customers, moving from the Modified Poly Sulfone (MPSU) tray to a Modified Polyphenylene Oxide (MPPO) tray.

MPPO trays are widely used in JEDEC industry for packaging, storage, and transportation of Integrated Circuits (ICs) and enable high-performance, ESD-safe engineering plastic that offers thermal stability, mechanical strength, and chemical resistance, making it ideal for semiconductor manufacturing and logistics.



(picture is for example only)

Tray	Intel Tray Part Number	Color	Bake	Tray Dimensions	Tray Thickness
MPSU	127-1717-A13	Black	125°C Bake/140°C MAX	322.6 x 136 mm (12.7 x 5.35 in)	7.62 mm
MPPO	127-1717-A19	Black	150°C MAX	322.6 x 135.9 mm (12.7 x 5.35 in)	7.62 mm

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Customers may see both MPSU and MPPO trays during the transition to the new tray, even after the deployment date listed above, until all MPSU tray inventory has been depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	Spec Code	MM#
Intel® Ethernet Controller I350-AM2	NHI350AM2	S LJ3S	915801
Intel® Ethernet Controller I350-AM4	NHI350AM4	S LJ3Z	915799

PCN Revision History:

Date of Revision:

August 14, 2026

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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Asia Pacific/PRC Contact: apacgccb@intel.com

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